

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

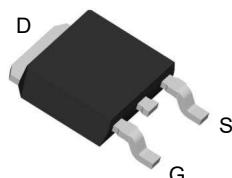
Product Summary



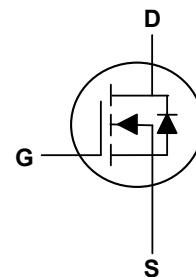
| | | |
|----------------------------------|------|----|
| V_{DS} | 100 | V |
| I_D | 14.6 | A |
| $R_{DS(ON)}$ (at $V_{GS}=10V$) | 100 | mΩ |
| $R_{DS(ON)}$ (at $V_{GS}=4.5V$) | 110 | mΩ |

Applications

- High Frequency Point-of-Load,Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch



TO-252 Top View



Absolute Maximum Ratings($T_c=25^\circ C$, unless otherwise noted)

| Parameter | Symbol | Rating | Units |
|--|---------------------------|------------|-------|
| Drain-Source Voltage | V_{DS} | 100 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current, $V_{GS} @ 10V^1$ | $I_D @ T_c = 25^\circ C$ | 14.6 | A |
| Continuous Drain Current, $V_{GS} @ 10V^1$ | $I_D @ T_c = 100^\circ C$ | 10 | A |
| Pulsed Drain Current ² | I_{DM} | 25 | A |
| Single Pulse Avalanche Energy ³ | EAS | 0.8 | mJ |
| Avalanche Current | I_{AS} | 4 | A |
| Total Power Dissipation ⁴ | $P_D @ T_c = 25^\circ C$ | 30 | W |
| Storage Temperature Range | T_{STG} | -55 to 150 | °C |
| Operating Junction Temperature Range | T_J | -55 to 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Typ | Max | Unit |
|--|-----------------|-----|-----|------|
| Thermal Resistance Junction-Ambient ¹ | $R_{\theta JA}$ | --- | 50 | °C/W |
| Thermal Resistance Junction-Case ¹ | $R_{\theta JC}$ | --- | 3 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|----------------------------|---|-----|------|-----------|------------------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$ | 100 | --- | --- | V |
| Static Drain-Source On-Resistance ² | $R_{\text{DS}(\text{ON})}$ | $V_{\text{GS}}=10\text{V}$, $I_D=5\text{A}$ | --- | --- | 100 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}$, $I_D=3\text{A}$ | --- | --- | 110 | $\text{m}\Omega$ |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$ | 1.2 | --- | 2.9 | V |
| Drain-Source Leakage Current | I_{DSS} | $V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$ | --- | --- | 10 | uA |
| | | $V_{\text{DS}}=80\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$ | --- | --- | 100 | |
| Gate-Source Leakage Current | I_{GSS} | $V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| Forward Transconductance | g_{fs} | $V_{\text{DS}}=5\text{V}$, $I_D=5\text{A}$ | --- | 14 | --- | S |
| Gate Resistance | R_g | $V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 3 | --- | Ω |
| Total Gate Charge | Q_g | $V_{\text{DS}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $I_D=5\text{A}$ | --- | 11.9 | --- | nC |
| Gate-Source Charge | Q_{gs} | | --- | 2.8 | --- | |
| Gate-Drain Charge | Q_{gd} | | --- | 1.7 | --- | |
| Turn-On Delay Time | $T_{\text{d}(\text{on})}$ | $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=3\Omega$, $I_D=5\text{A}$ | --- | 3.8 | --- | ns |
| Rise Time | T_r | | --- | 25.8 | --- | |
| Turn-Off Delay Time | $T_{\text{d}(\text{off})}$ | | --- | 16 | --- | |
| Fall Time | T_f | | --- | 8.8 | --- | |
| Input Capacitance | C_{iss} | $V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 450 | --- | pF |
| Output Capacitance | C_{oss} | | --- | 55 | --- | |
| Reverse Transfer Capacitance | C_{rss} | | --- | 16 | --- | |

Drain-Source Diode Characteristics

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--|-----------------|--|-----|-----|------|------|
| Continuous Source Current ^{1,5} | I_S | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 14.6 | A |
| Pulsed Source Current ^{2,5} | I_{SM} | | --- | --- | 25 | A |
| Diode Forward Voltage ² | V_{SD} | $V_{\text{GS}}=0\text{V}$, $I_S=1\text{A}$, $T_J=25^\circ\text{C}$ | --- | --- | 1.2 | V |

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

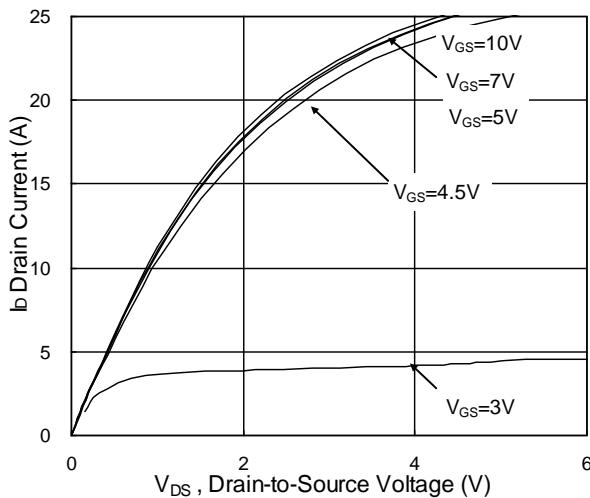


Fig.1 Typical Output Characteristics

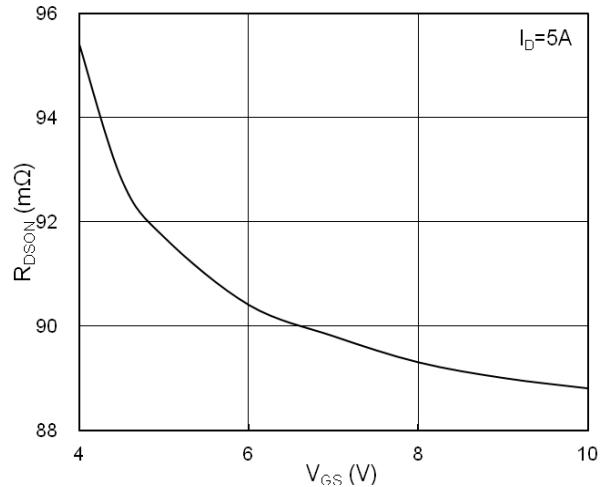


Fig.2 On-Resistance vs. Gate-Source

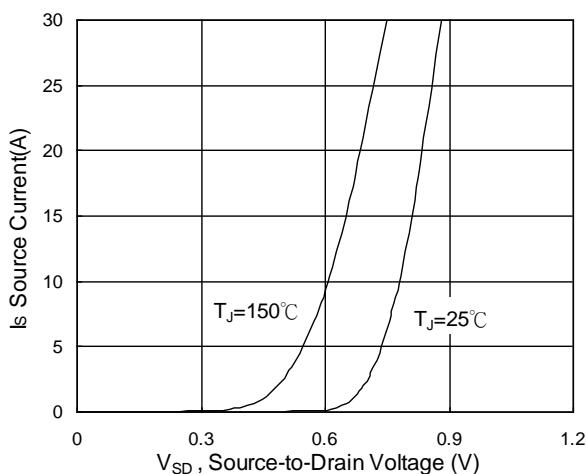


Fig.3 Forward Characteristics Of Reverse

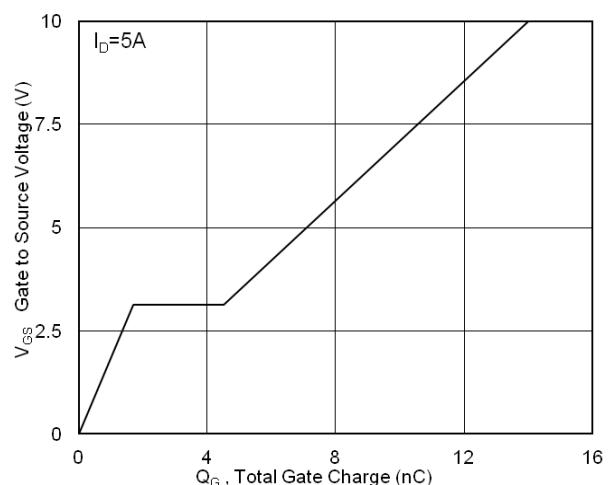


Fig.4 Gate-Charge Characteristics

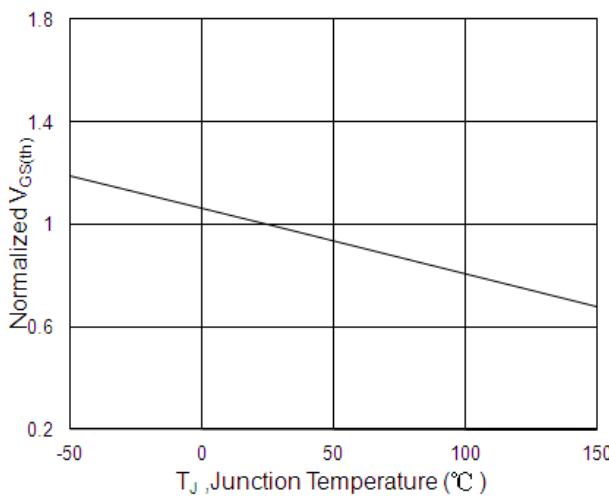


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

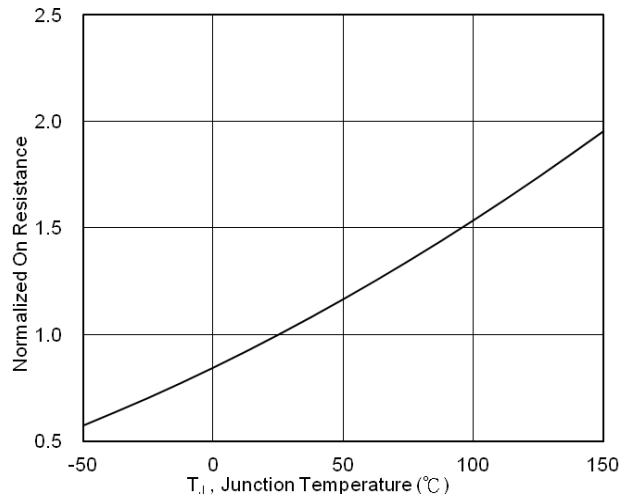
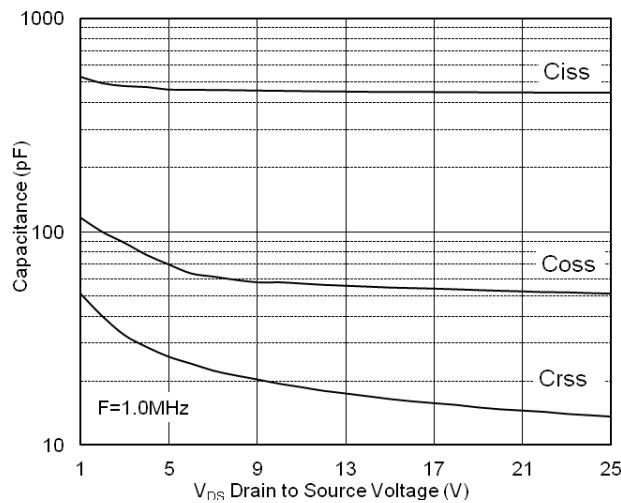
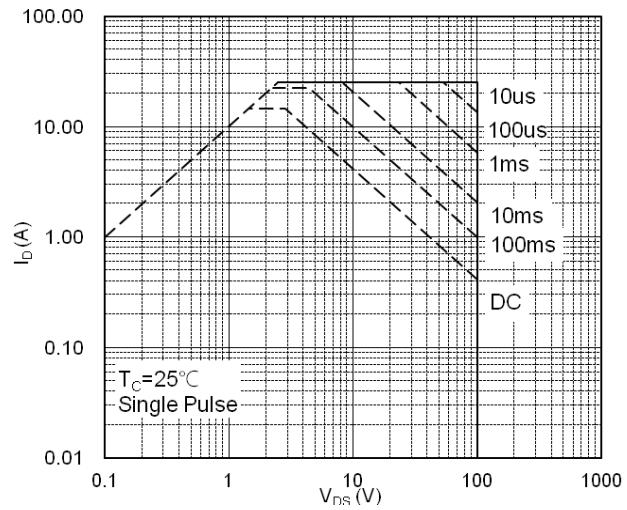
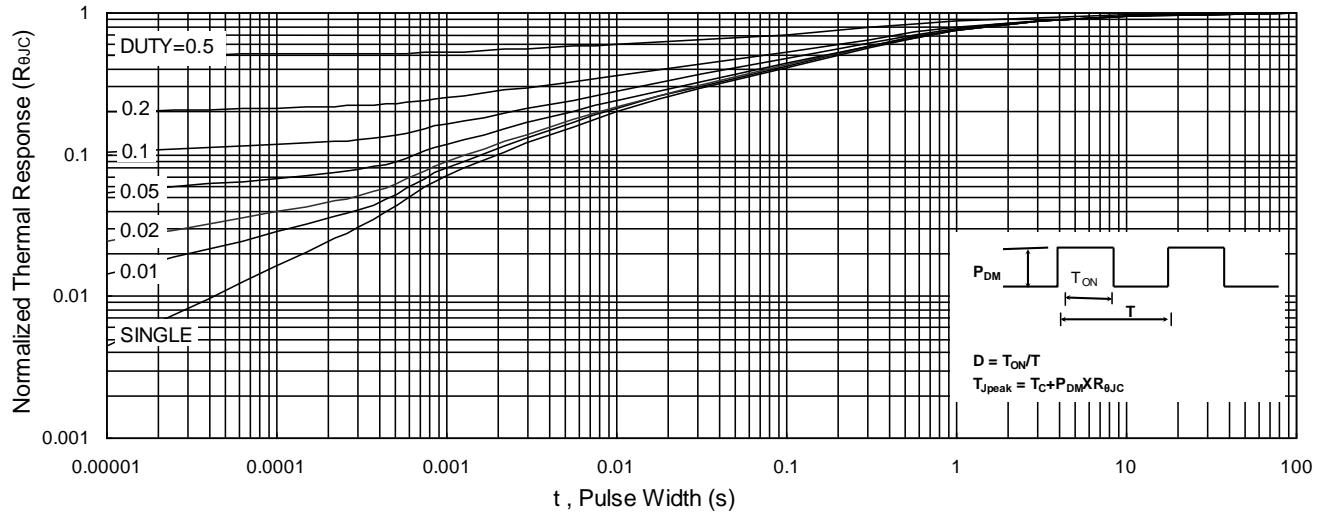
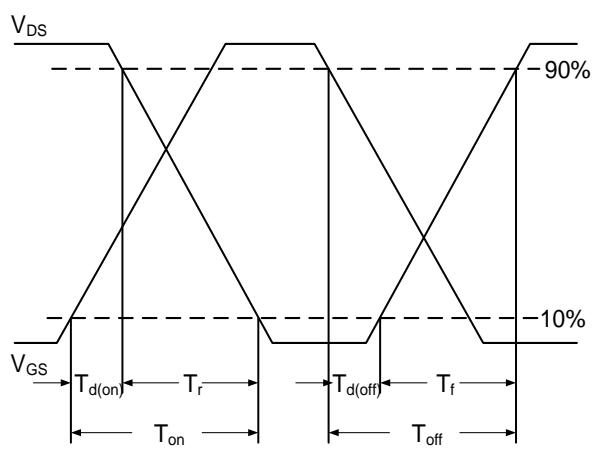
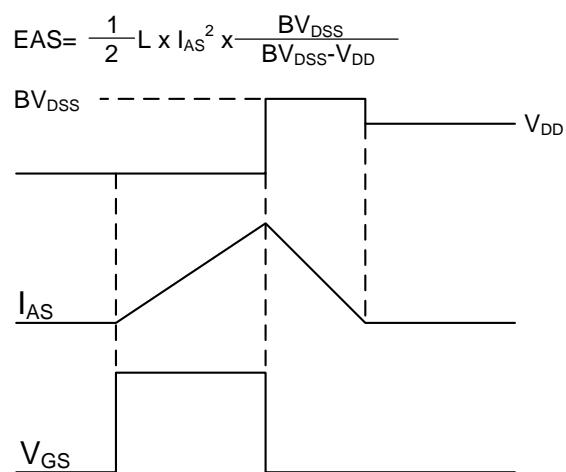
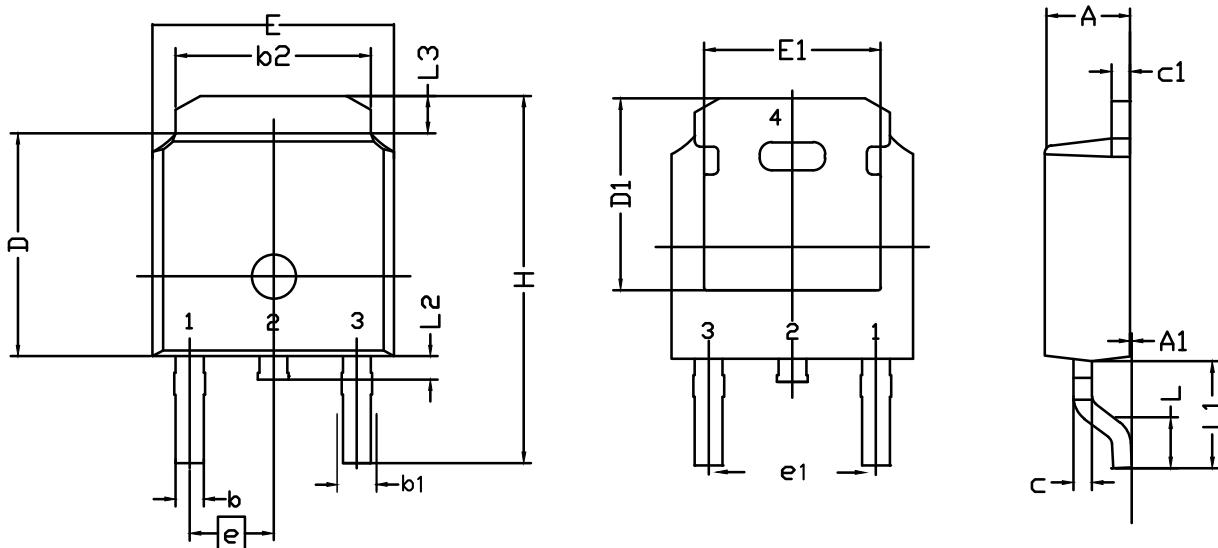


Fig.6 Normalized $R_{DS(on)}$ vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform

TO-252 Package Outline Dimensions



| Symbol | Dimensions (unit:mm) | | | Symbol | Dimensions (unit:mm) | | |
|----------------------|-----------------------------|------------|------------|----------------------|-----------------------------|------------|------------|
| | Min | Typ | Max | | Min | Typ | Max |
| A | 2.20 | 2.30 | 2.38 | E | 6.40 | 6.60 | 6.731 |
| A₁ | 0.00 | 0.10 | 0.20 | E₁ | 4.40 | -- | -- |
| b | 0.64 | 0.76 | 0.89 | e | 2.286 BSC | | |
| b₁ | 0.77 | 0.85 | 1.14 | e₁ | 4.572 BSC | | |
| b₂ | 5.00 | 5.33 | 5.46 | H | 9.40 | 10.00 | 10.40 |
| c | 0.458 | 0.508 | 0.610 | L | 1.40 | 1.52 | 1.77 |
| C₁ | 0.458 | 0.508 | 0.620 | L₁ | -- | 2.743 | -- |
| D | 5.98 | 6.10 | 6.223 | L₂ | 0.60 | 0.80 | 1.01 |
| D₁ | 5.20 | 5.25 | 5.38 | L₃ | 0.90 | 1.06 | 1.25 |